

Product Features (Please use the Product Drawing for all design activity)

Housing Related Features:

Product Type Features:

- Product Type = Receptacle
- Number of Positions = 64
- PCB Mount Angle = Vertical
- Keyed = No
- Comment = IEEE 1386 Mezzanine Connector.

- Housing Color = Black
- Housing Material = High Temperature Thermoplastic
- Housing Flammability Rating = UL 94V-0
- Housing Material Temperature = High

Industry Standards:

Body Related Features:

- Centerline (mm [in]) = 1.00 [0.039]
- Board-to-Board Stack Height (mm [in]) = 8.00 [0.315], 9.00 [0.354], 10.00 [0.394]
- Locating Posts = With
- Vacuum Cover = Without
- Number of Rows = Dual

- RoHS/ELV Compliance = ELV compliant, 5 of 6 Compliant
- Lead Free Solder Processes = Wave solder capable to 240°C, Wave solder capable to 260°C, Wave solder capable to 265°C, Reflow solder capable to 245°C, Reflow solder capable to 260°C, Pin-in-Paste capable to 245°C, Pin-in-Paste capable to 260°C

Contact Related Features:

- Family Name = Free Height
- Contact Layout = In-Line
- Contact Material = Copper Alloy
- Contact Mating Area Plating = Gold (30)
- Contact Termination Area Plating = Tin-Lead over Nickel

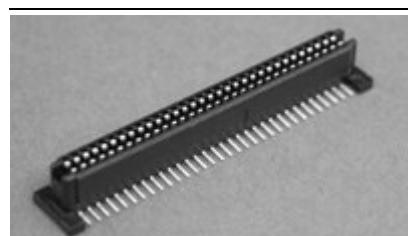
Packaging Related Features:

- Packaging Method = Tape & Reel

Other:

- Brand = AMP

Product Details for 120521-1



120521-1

.4mm, .5mm, .6mm, .8mm, 1mm, Fine Pitch, Surface Mount, Stacking Bd-to-Bd Connectors

 [5 of 6 RoHS/ELV Compliant \(Find RoHS Compliant Alternates/Compliance Statement\)](#)

Product Highlights:

- Receptacle
- Family Name = Free Height
- 1.00 mm Centerline
- Number of Positions = 64
- In-Line Contact Layout

 [Active](#)

[View all Features](#)

- △ HOUSING MATERIAL: HIGH TEMPERATURE THERMOPLASTIC. COLOR: BLACK.
CONTACT MATERIAL: PHOSPHOR BRONZE
- △ CONTACT FINISH: 0.00381 MINIMUM MATTE TIN-LEAD (93-7)
ON SOLIDER AREA, 0.00076 MINIMUM GOLD ON MATING AREA,
BOTH OVER 0.00127 MINIMUM NICKEL ON ENTIRE CONTACT.
- △ DATUM LOCATIONS AND BASIC DIMENSIONS TO BE ESTABLISHED BY THE
CUSTOMER; CONSULT AMPLIFYING NERING WHEN PLACING MULTIPLE
CONNECTORS ON A PC BOARD.
- 4. PACKAGED IN TAPE ON REEL PER EIA-481.
- △ I-5±0.05 DIAMETER HOLE SHOULD BE USED IF PLACED
ON PCB WITH VACUUM PLACEMENT EQUIPMENT.
- △ SHORTER SOLDER LANDS MAY BE USED PER EIA 700AAAB, HOWEVER 2.4
LENGTH ASSURES OPTIMUM SOLDER FILLET REGARDLESS OF
MANUFACTURE OF CONNECTOR.
- △ REFERRED TO AS DIM H = 5.30±0.1 IN EIA 700AAAB SPECIFICATION.
- △ CONTACT FINISH: 0.00381 MINIMUM MATTE TIN-LEAD (93-7)
ON SOLIDER AREA, 0.00076 MINIMUM GOLD ON MATING AREA.

